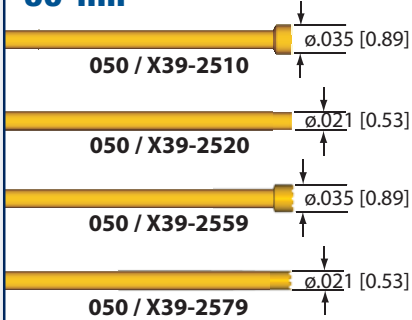


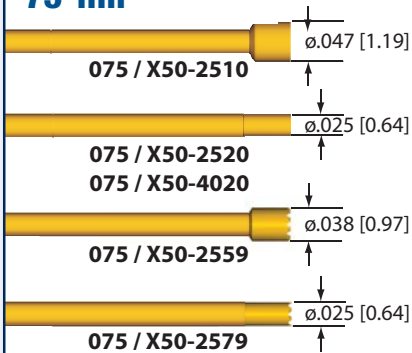
# Tip Styles for Solder Bump Micro Access Technologies

September 2011

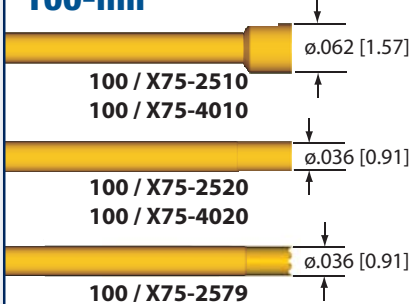
## 50-mil



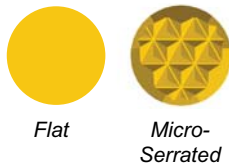
## 75-mil



## 100-mil



### Tip Style Top View

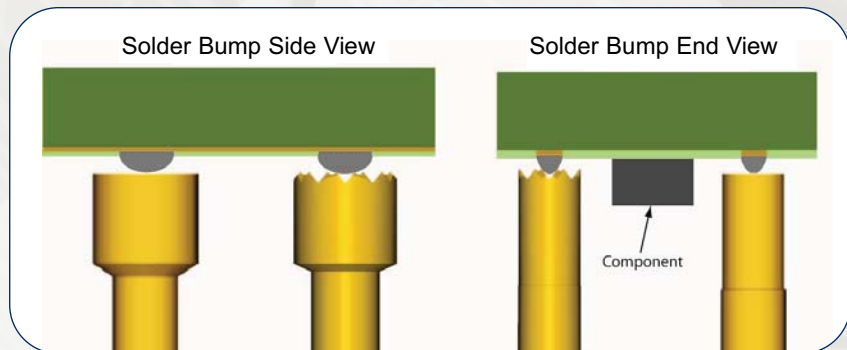


QA Technology offers a variety of headed and headless tip styles designed for use with solder bump micro access technologies: our flat tip (**10 or 20**) and micro-serrated (**59 or 79**).

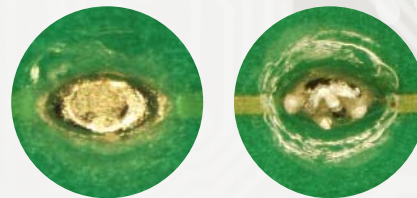
The newer micro-serrated tips are an added solution for extreme circumstances where contaminants, fluxes or oxides are too great to make reliable contact with flat tips.

Upon actuation, the force of the spring probe compresses the solder bump breaking through any flux residues and contaminants, providing a reliable electrical contact. Our headless versions are available for situations where nearby components are located too close to the intended solder bump target.

Available sizes are outlined to the left and are available in both Conventional Probe and X Probe Socketless Series.



Headed and headless versions of flat and micro-serrated tip styles available for solder bump micro access technologies.



Witness marks of both the flat (left) and micro-serrated (right) tips breaking through flux.

For detailed specifications, samples or pricing please contact your QA Customer Service Representative at (603) 926-0348 or [sales@qatech.com](mailto:sales@qatech.com).

All dimensions are in inches [mm]. All spring forces are in ounces [gms].